

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6890K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

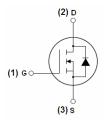
General Features

- $V_{DS} = 68V, I_D = 90A$
 - $R_{DS(ON)} < 7.5 \text{m}\Omega$ @ $V_{GS} = 10V$ (Typ:6.5 m Ω)
- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply

100% UIS TESTED! 100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



TO-252-2L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6890K	NCE6890K	TO-252-2L	-	-	_

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	68	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	90	Α
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	63	Α
Pulsed Drain Current (Note 1)	I _{DM}	320	А
Maximum Power Dissipation	P _D	130	W
Derating factor		0.86	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	380	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$

Thermal Characteristic

Thermal Resistance.Junction-to-Case (Note 2)	Ross	1 15	°C/W
Thermal Resistance, Junction-to-Case	МθJc	1.15	CIVV



Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	<u>.</u>					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	68	73	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =68V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•		•			•
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	6.5	7.5	mΩ
Forward Transconductance	g Fs	V _{DS} =10V,I _D =20A	20	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 00\/\/ 0\/	-	3300	-	PF
Output Capacitance	C _{oss}	V_{DS} =30V, V_{GS} =0V,	-	450	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	170	-	PF
Switching Characteristics (Note 4)	•		•			•
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	V_{DD} =30V, I_D =20A	-	94	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10V, R_{GEN} =6 Ω	-	46	-	nS
Turn-Off Fall Time	t _f		-	32	-	nS
Total Gate Charge	Q_g	V 00V/1 00A	-	35	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =30V,I _D =20A,	-	11	-	nC
Gate-Drain Charge	Q_gd	V _{GS} =10V	-	9	-	nC
Drain-Source Diode Characteristics			•			•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current (Note 2)	Is	-	-	-	90	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =20A	-	78	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	51	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD				

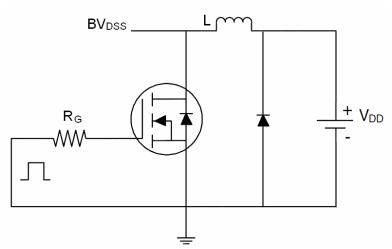
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** E_{AS} condition:Tj=25 $^{\circ}$ C,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25 Ω

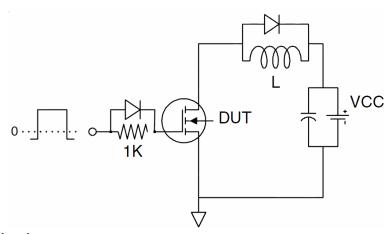


Test Circuit

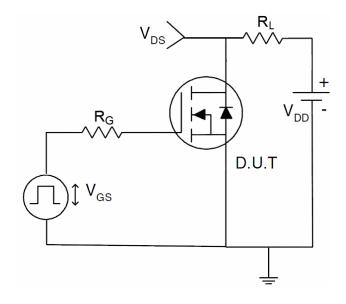
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

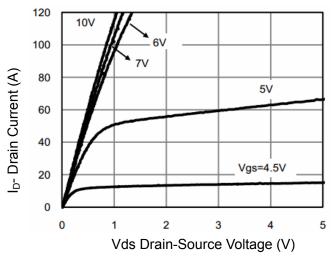


Figure 1 Output Characteristics

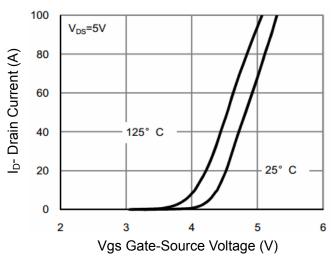


Figure 2 Transfer Characteristics

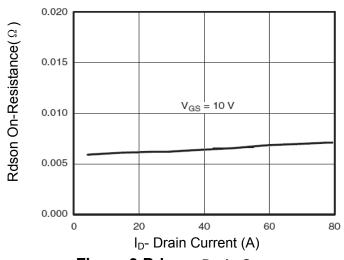


Figure 3 Rdson- Drain Current

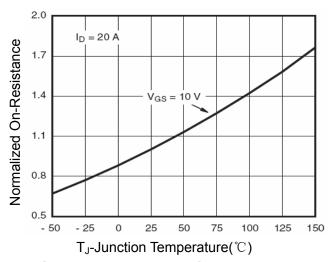


Figure 4 Rdson-JunctionTemperature

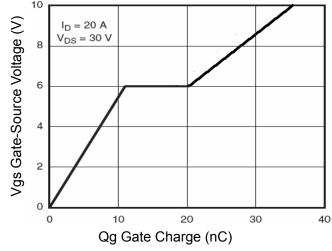


Figure 5 Gate Charge

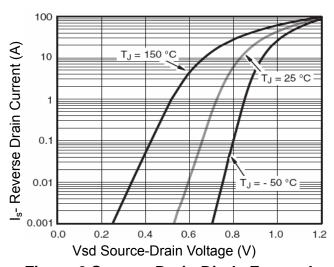
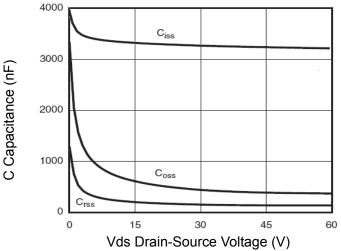


Figure 6 Source- Drain Diode Forward





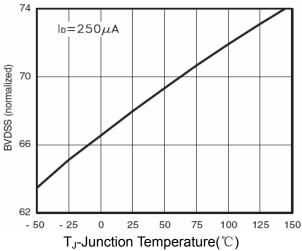
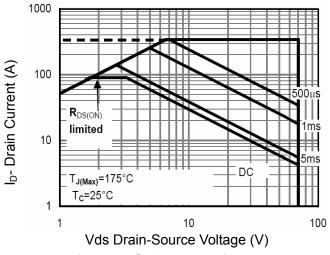


Figure 7 Capacitance vs Vds Figure 9 BV_{DSS} vs Junction Temperature



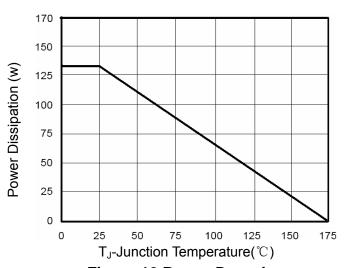


Figure 8 Safe Operation Area

Figure 10 Power De-rating

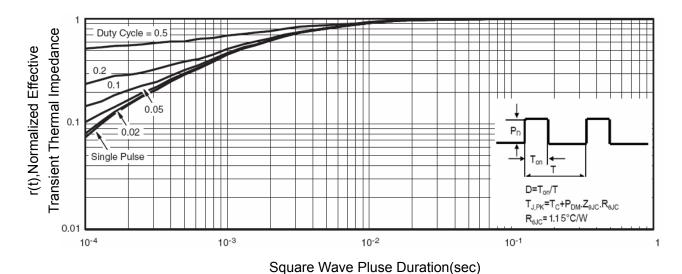
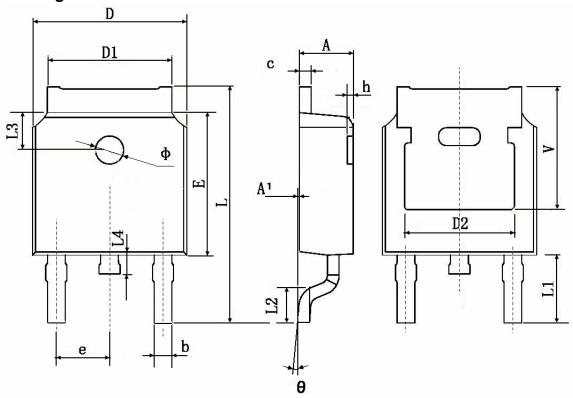


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-252 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.83	0 TYP.	0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.90	0 TYP.	0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.60	0 TYP.	0.063	TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.35	0 TYP.	0.211 TYP.		



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